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Application of: Robert J. Small

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Application No. 09/903,064

Art Unit: 1751

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Examiner: Gregory E. Webb

For: **METHOD OF CHEMICALLY
MECHANICALLY POLISHING SUBSTRATES**

Atty No.: 060937-0091-US

U.S. Patent and Trademark Office
Randolph Building
401 Dulany Street
Alexandria, Virginia 22314

Sir:

**SUBMISSION OF REVOCATION OF ORIGINAL POWER OF ATTORNEY
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Enclosed is a copy of the Revocation of Original Power of Attorney and Grant of New Power of Attorney by the Assignee, EKC Technology, Inc. Assignee directs the Patent and Trademark Office to send all future correspondence to:

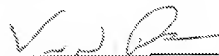
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If there is any fee due in connection with the filing of this Submission, please charge the fee to Morgan, Lewis & Bockius LLP Deposit Account No. 50-0310.

Respectfully submitted,

January 28 2009

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REVOCATION AND POWER OF ATTORNEY

Commissioner for Patents
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Sir:

EKC Technology, Inc., owner of the entire right, title and interest in, to and under the inventions described and claimed in the patent applications identified in the attached Schedule A, hereby revokes all previous powers of attorney and appoints Morgan, Lewis & Bockius LLP, Customer Number 009629, and each of them, its attorneys, to prosecute each of these patent applications, and to transact all business in the Patent and Trademark Office connected therewith.

Please direct all future correspondence to Customer No. 009629, Patent Support Unit, Morgan, Lewis & Bockius LLP, 1111 Pennsylvania Avenue, N.W., Washington, D.C. 20004, and direct all telephone calls to Morgan, Lewis & Bockius LLP at 202-739-3000.

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Date: 29 March 2004

Signature:

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Schedule A

| Patent No. | Title | Inventor(s) | Filing Date | New Attorney Docket No. | Former Attorney Docket No. |
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